

# CUSTOMER MODEL NO. / TITLE MINI DIN 4 POS WITH OPTICAL CONNECTOR

DATASHEET FOR FC6842135TR

PAGE: 1 OF 7 DATE: OCT,05,2005

### 1. Scope

This specification covers the requirements for I/O signal and video machine connecting with optical connector.

# 2. Adapted plug

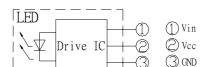
Adapted plug as Fig.4.

#### 3. The outlook structure and dimension

The outlook and plated stripped with vision shall be capable of correct using and without loosing and breakdown.

#### 4. Rated

- 4-1 Temperature and humidity range for using: -25~70°C, 85% RH max.
- 4-2 Temperature and humidity range for storage: -40~70 °C, 85% RH max
- 4-3 Supply voltage:-0.5 to 7V
- 4-4 Input voltage:-0.5 to Vcc +0.5V
- 4-5 Operating voltage: 2.75 to 5.25V
- 4-6 Signal transmission speed:16Mbps



Internal equivalent circuit

### 5. Status of testing

#### 5-1 Standard condition

All measurement and tests shall be made at temperature of  $15\sim35$  °C and relative humidity of  $25\sim80\%$ , air pressure of  $86\sim106$ kPa.

If the justification has problem, at temperature  $20\pm2\,^{\circ}\text{C}$  and relative humidity of  $60\sim70\%$ , air pressure of  $86\sim106\text{kPa}$ .

### 5-2 After testing

In test room at temperature of  $15\sim35\pm1$  °C and relative humidity of  $75\sim77\%$ , air pressure of  $86\sim106$ kPa.

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6. Electrical efficiency

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit.
Peak emission wavelength	λр		630	660	690	nm
Optical power output coupling with fiber	Pc	Refer to Fig.1	-21	-18	-15	dBm
Dissipation current	Icc	Refer to Fig.2	3	-	10	mA
High level input voltage	$V_{iH}$	Refer to Fig.2	2	-	-	V
Low level input voltage	$ m V_{iL}$	Refer to Fig.2	-	-	0.8	V
Low → High delay time	$t_{pLH}$	Refer to Fig.3	-	-	120	ns
High → Low delay time	$t_{ m pHL}$	Refer to Fig.3	-	-	120	ns
Pulse width distortion	Δtw	Refer to Fig.3	-25	-	25	ns
Jitter	Δtj	Refer to Fig.3	-	-	20	ns

7. Mechanical efficiency

7. IVICC	chanical efficie	псу	T			
No.	Ite	em	Test method	Character		
7-1	Mating force	OPTO conn.	As Fig.4, use adapted gauge plug for testing.	39.2N max		
7-2	Withdrawal force OPTO conn.		As Fig.4, use adapted gauge plug for testing.	5.9N to 39.2N		
7-3	Durability	OPTO conn.	As Fig.1, use adapted gauge plug for testing, 500cycles insertion and withdrawal.	Satisfy with 7-1,7-2 and the outlook without breakdown or unnormal.		
7-4	Chape test		After inserting a plug (as Fig.4) for the test. It gains 5 second of upper and lower either side torque of 1N five times.	To be mated without mechanical abnormality.		
7-5	Vibration resistance		The test sample is soldered on the P.W.B And then the simple vibration which change			

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#### 8. Environmental test

midity test  nperature ling test	Take forth and back cycles 5 times form the	Satisfy with 7-1,7-2 the outlook without unnormal. (OPTO)
•	adapted plug and jack. Upon completion of above process for 1.5~2 hours.  Execute the temperature testing as following.	
inig test	-25 ° C	
ry heat	The test sample shall be left at a temperature of 70±2 °C for 240h. And then it shall be kept under standard atmospherics condition for 1h, after which measurement shall be made. (Refer to JIS C 0021)  The test sample shall be left at a temperature of -25±3 °C of 240h. And then it shall be kept under	Satisfy with 7-1,7-2 the outlook without unnormal. (OPTO)
ry		heat standard atmospherics condition for 1h, after which measurement shall be made. (Refer to JIS C 0021)  The test sample shall be left at a temperature of

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No.	Item	Test method	Character
8-5	Solder ability test	JIS C0053 rule applied use rosin liquid 25% for 3seconds.  Temperature of solder: 235±3°C  Time of dip: 5sec  Length of dip: 4±0.5mm.	A new uniform coating of solder shall be cover more than 95% of the surface being immersed.
8-6	Resistance to soldering heat	Solder bath method  Solder temperature: $260 \pm 3 ^{\circ}\text{C}$ Immersion time: $5 \pm_{0}$ sec., 2times  Immersion depth: Up to the surface of the board.  Thickness of printed wiring board: 1.6mm  Material:  Dimensions of component holes in the printed wiring board shall be in accordance with those specified in this specification.  Soldering iron method  Bit temperature: $380 \pm 10 ^{\circ}\text{C}$ Application of soldering iron: $3 \pm_{0}$ sec  However, excessive pressure shall not be applied to the terminal.	Satisfy with 7-1,7-2 the outlook without unnormal. (OPTO)

Remark: If the jack with "switch,,, the out connector plug test is also used.

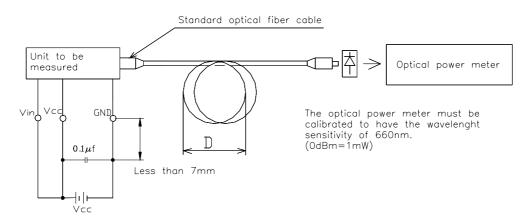
CUSTOMER MODEL NO. / TITLE
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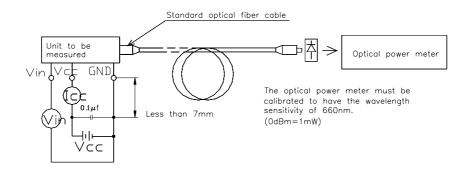
Fig.1 Measuring Method of Optical Output Coupling with Fiber.



Notes: (1) OC-08 Vcc=3.0V (State of operating).

(2) To bundle up the standard fiber optic cable, make it into a loop with the diameter D=10cm or more. (The standard fiber optic cable will be specified elsewhere.)

Fig.2 Measuring Method of Input Voltage and Supply Current.



Input conditions and judgment method.

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Condition	Judgment method
V <sub>in</sub> =2.1V or more.	-21 ≤Pc ≤-15dBm, Icc=13mA or less.
V <sub>in</sub> =0.8V or less.	Pc≤-36dBm, Icc=13mA or less.

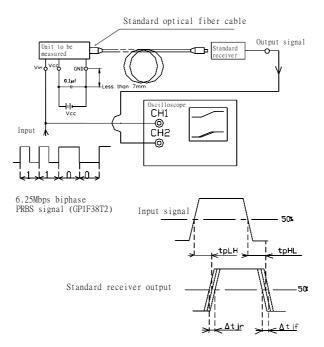
Note) Vcc=3.0V (State of operating).

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Fig.3 Measuring Method of Pulse Response and Jitter.



### Test item

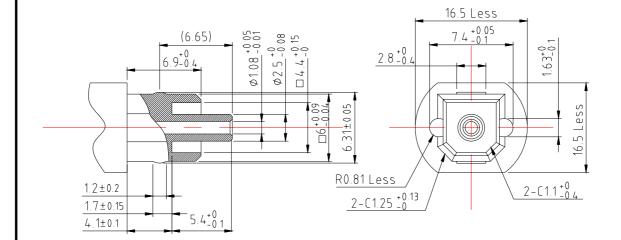
Test item	Symbol	Test condition
Low → High pulse delay time	$t_{ m PLH}$	Refer o the above prescriptions
High → Low pulse delay time	$t_{ m PHL}$	Refer to the above prescriptions
Pulse width distortion	Δtw	$\Delta tw = t_{PHL} - t_{PLH}$
Low → High Jitter	Δtjr	Set the trigger on the rise of input signal to measure the jitter of the rise of output
High → Low Jitter	Δtjf	Set the trigger on the fall of input signal to measure the jitter of the rise of output

Notes: (1) The waveform write time shall be 4 seconds. But do not allow the waveform to be distorted by increasing the brightness too much.

- (2) Vcc=3.0V (State of operating)
- (3) The probe for the oscilloscope must be more than  $1M\Omega$  and less than 10pF.

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# Fig.4 Adapted plug



Unit:mm

# Cliff Electronic Components Ltd.

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OPTICAL RECEIVING JACK	FC6842135TR	DATE:	APR,0,2003

Fiber optic receiving module for digital audio interface and navigation system.

#### Features:

- (1) Conform to EIAJ standard CP-1201 (for Digital Audio interfaces Including Fiber Optical inter-connectors).
- (2) A self-tapping hole for easy attachment to Audio Equipments panels.
- (3) High speed signal receiving (12.5Mbps NRZ signal)

# 1. Maximum Ratings

 $(Ta=25^{\circ}C)$ 

Parameter	Symbol	Rating	Unit
Storage Temperature	$T_{stg}$	<b>-</b> 40 ~ 70	$^{\circ}\! \mathbb{C}$
Operating Temperature	$T_{opr}$	<b>-</b> 20 ~ 70	$^{\circ}\! C$
Supply Voltage	Vcc	<b>-</b> 0.5 ~ 6	V
High Level Output Current	$I_{OH}$	-1	mA
High Level Output Current	$I_{OL}$	5	mA
Soldering Temperature	Tsol	260 (1)	$^{\circ}\! \mathbb{C}$

Note (1): Soldering time  $\leq 10$  seconds (At a distance of 1mm from the package.)

# 2. Recommended Operating Conditions

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	Vcc	4.75	5.0	5.25	V

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OPTICAL RECEIVING JACK PAGE: 2 OF 7
DATE: APR,0,2003

3. Optical-electro Characteristics (Ta =  $25^{\circ}$ C, Vcc = 5V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit.
Data Rate		NRZ Code (2)	0.1	-	12.5	Mb/s
Transmission Distance		Using APF (3), Using OC0805T	0.2	-	5	M
Pulse Width Distortion (4)	Δtw	Pulse Width = 147ns Pulse Cycle = 294ns C <sub>L</sub> = 10pF Using OC0805T	-15	-	15	ns
Maximum Receivable Power	P <sub>MAX</sub>	12.5Mb/s, Using APF	-	-	-14.5	dBm
Minimum Receivable Power	P <sub>MIN</sub>	12.5Mb/s, Using APF	-24	-	-	dBm
Current Consumption	$I_{CC}$		-	15	40	mA
High Level Output Voltage	V <sub>OH</sub>		2.4	4.8	Vcc	V
Low Level Output Voltage	V <sub>OL</sub>		-	0.2	0.4	V
Rise time	t <sub>r</sub>	Refer to "Test Circuit,,	-	10	20	ns
Fall time	$t_{\rm f}$	Refer to "Test Circuit,,	-	10	20	ns
Low→High delay time	t <sub>p</sub> LH	Refer to "Test Circuit,,	-	100	180	ns
High→Low delay time	t <sub>p</sub> HL	Refer to "Test Circuit,,	-	100	180	ns

Note (2): When non-modulated signal (optical all high or all low level signal) is inputted, output signal is not stable.

When modulated optical high level signal is received, output signal is high.

When modulated optical low level signal is received, output signal is low.

The duty factor must be maintained between 25 to 75%.

Note (3): All Plastic Fiber (970 / 1000μm).

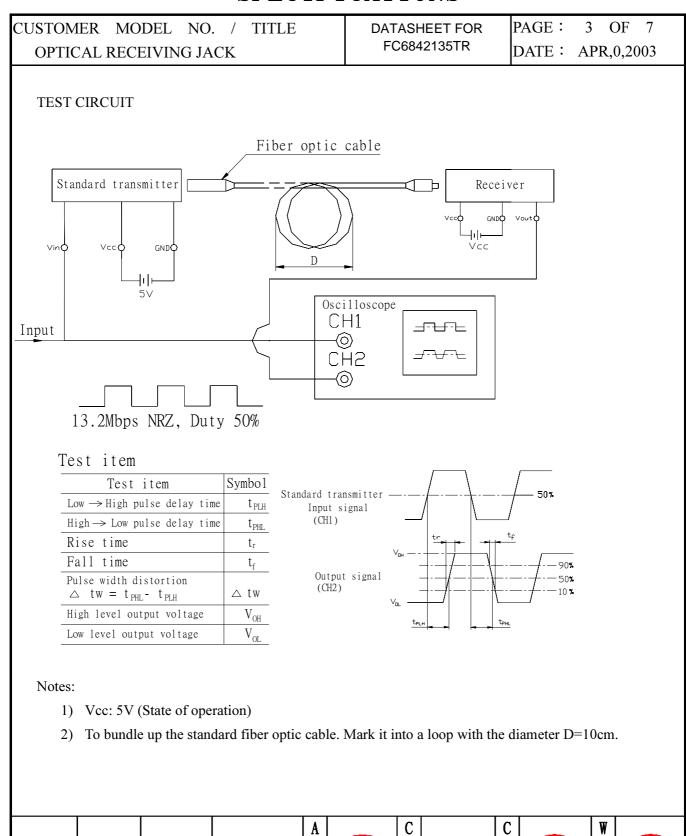
Note (4): Between input of transmitting module and output of OC0805T.

### 4. Mechanical Characteristics (Ta= 25°C)

4-1

Parameter	Condition	MIN.	TYP.	MAX.	Unit
Insertion Force.	Using JYE TAI OC-0801P,	-	-	40	N
Withdrawal Force.	Initial value	4	-	40	N
Torque for Self-Tap	Using self-tapping Screw (TP3×8)	58.8	-	78.4	N · cm

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CUSTOMER MODEL NO. / TITLE PAGE: 4 OF 7 DATASHEET FOR FC6842135TR DATE: APR,0,2003 OPTICAL RECEIVING JACK 5. Application Circuit Fiber optic connector insertion side Fiber Optic Receiving Modbule Less than 7 mm  $0.1 \mu F$ Vcc **GND** Vout ( Bottom View ) 6. Required Optical Fiber with Fiber Optic Connectors  $\mathsf{C}$ C A P H H R V K K T 宗暉 D D D REV. NAME DATE REMARK

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#### 7. Precautions on Use

### (1) Maximum rating

The maximum ratings are the limit values which must not be exceeded during operation of device. None of these rating value must not be exceeded. If the maximum rating value is exceeded, the characteristics of devices may never be restored properly. In extreme cases, the device may be permanently damages.

### (2) Soldering

Optical modules are comprised of internal semiconductor devices. However, in principle, optical modules are optical components. During soldering, ensure that flux does not contact with the emitting surface or the detecting surface. Also ensure that proper flux removal is conducted after soldering.

Some optical modules come with a protective cap. The protective cap is used to avoid malfunction when the optical module is not in use. Note that it is not dust or waterproof.

As mentioned before, optical modules are optical components. Thus, in principle, soldering where there may be flux residue and flux removal after soldering is not recommended. **CLIFF** recommend that soldering be performed without the optical module mounted on the board.

Then, after the board has been cleaned, the optical module should be soldered on to the board manually.

If the optical module cannot be soldered manually, use non-halogen (chlorine-free) flux and make sure, without cleaning, there is no residue such as chlorine. This is one of the ways to eliminate the effects of flux. In such a cases, be sure to check the devices' reliability.

#### (3) Noise resistance

It is believed that the use of optical transfer devices improve noise resistance. In theory, optical fiber is not affected by noise at all. However, receiving modules which handle signals whose level is extremely small, are susceptible to noise.

The optical module is to be used in an area which is susceptible to radiated noise, increase the shielding by covering the optical module and the power line filter with a metallic cover.

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#### (4) Vibration and shock

This module is plastic sealed and has its wire fixed by resin. This structure is relatively resistant to vibration and shock. In actual equipment, there are sometime cases in which vibration, shock, or tress is applied to soldered parts or connected parts, resulting in lines cut.

A care must be taken in the design of equipment which will be subject to high levels of vibration.

### (5) Support pins

The jack has support pins in order to fix itself to the PCB temporary. Please make the hole for these pins in the PCB under the condition described in board layout hole pattern.

#### (6) Panel attachment

jack has hole for panel attachment. Please be sure to attach it to panel with self-tapping screw.

#### (7) Solvent

When using solvent for flux removal, do not use a high acid or high alkali solvent. Be careful not to pour solvent in to the optical connector ports. If solvent is inadvertently poured in to them, clean it off using cotton tips.

### (8) Supply voltage

Use the supply voltage within the recommended operating condition (Vcc =  $5\pm0.25$ V). Make sure that supply voltage does not exceed the maximum rating value of 7V, even for an instant.

### (9) Interface

The jack has a TTL interface. It can be interfaced with any TTL-compatible C-MOS IC.

#### (10) Output

If the receiver output is at low and is connected to the power supply, or if the output is high and is connected to GND, the internal IC may be destroyed.

#### (11) Soldering condition

Solder at 260°C or less for no more than ten seconds.

#### (12) Repeated operation:

Inserting and withdrawing shall be made at a speed of 20 times or less/min using mating plug (Refer to clause 4). 500 times.

### (13) Precautions when disposing of devices and packing materials.

When disposing devices and packing materials, follow the procedures stipulated by local regulations in order to protect the environment against contamination.

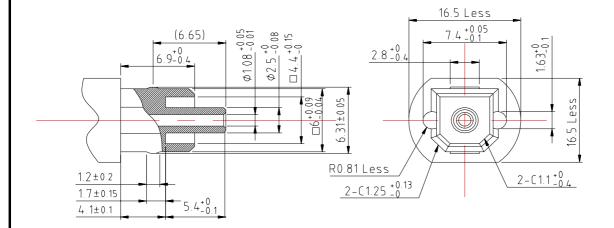
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### (14) Precautions during use

**CLIFF** is continually working to improve the quality and the reliability of their products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and their vulnerability to physical stress. It is the responsibility of the buyer, when utilizing **CLIFF** products, to observe standards of safety, and to avoid situations in which the malfunction or failure of a **CLIFF** product could cause loss of human life, bodily injury or damage to property.

# Mating plug



Unit:mm

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Document No.	Document name	Rev.	DATE
01-E	Management standards for "Environment-related substances to be controlled"	1 2	PAGE: 1 OF 2 DATE: APR,20,2009

- 1. This part should not contain any substances which are specified in follow .(Except cadmium is less than 5ppm, Lead is under 90ppm)
- 2. In this case, pre-processing methods and measurement methods shall conform to ROHS.

3. List of "Environment-related Substances to be Controlled ('The Controlled Substances')"

Allowable concentration	3. List of "Environme	ent-related Substances to be Controlled ('The Controlled	Substa	ances')"					
Heavy metals    Cadmium and cadmium compounds   Less   5ppm		Substances							
Heavy metals  Lead in the plastic,rubber,paints,ink  Mercury and mercury compounds  Hexavalent chromium compounds  Nickel and Nickel compounds (at present only ASUS and Silitek)  Polychlorinated biphenyls (PCB)  Polychlorinated naphthalenes (PCN)  Short-chain chlorinated paraffins (SCCP)  Polychlorinated terphenyls (PCT)  Other chlorinated organic compounds  Polybrominated biphenyls (PBB)  Polybrominated diphenylethers (PBDE)(including decabromodiphenyl ether [DecaBDE])  Other brominated organic compounds  Organic tin compounds (tributy tin compounds, Triphenyl tin compounds)  Asbestos  Specific azo compounds  Formaldehyde  Polyvinyl chloride (PVC) and PVC blends		Cadmium and cadmium compounds							
Heavy metals  Mercury and mercury compounds  Hexavalent chromium compounds  Nickel and Nickel compounds (at present only ASUS and Silitek)  Polychlorinated biphenyls (PCB)  Polychlorinated naphthalenes (PCN)  Short-chain chlorinated paraffins (SCCP)  Polychlorinated terphenyls (PCT)  Other chlorinated organic compounds  Polybrominated biphenyls (PBB)  Polybrominated diphenyls (PBB)  Polybrominated diphenylethers (PBDE)(including decabromodiphenyl ether [DecaBDE])  Other brominated organic compounds  Organic tin compounds (tributy tin compounds, Triphenyl tin compounds)  Asbestos  Specific azo compounds  Formaldehyde  Polyvinyl chloride (PVC) and PVC blends		Lead and lead compounds	Less	90ppm					
Mercury and mercury compounds Hexavalent chromium compounds Nickel and Nickel compounds (at present only ASUS and Silitek)  Polychlorinated biphenyls (PCB) Polychlorinated naphthalenes (PCN) Short-chain chlorinated paraffins (SCCP) Polychlorinated terphenyls (PCT) Other chlorinated organic compounds  Polybrominated biphenyls (PBB) Polybrominated biphenyls (PBB) Polybrominated diphenylethers (PBDE)(including decabromodiphenyl ether [DecaBDE]) Other brominated organic compounds  Organic tin compounds (tributy tin compounds, Triphenyl tin compounds)  Asbestos  Specific azo compounds  Formaldehyde Polyvinyl chloride (PVC) and PVC blends	Haavy matala	Lead in the plastic,rubber,paints,ink	Less	50ppm					
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Formaldehyde Polyvinyl chloride (PVC) and PVC blends	Asbestos								
Polyvinyl chloride (PVC) and PVC blends	Specific azo compour	nds							
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Fooming aushion material (FDS - FDE - FDD)	Polyvinyl chloride (P	Polyvinyl chloride (PVC) and PVC blends							
TOAITING CUSINON MAICHAI (EFS ' EFE ' EFF)	Foaming cushion mat	erial (EPS \ EPE \ EPP)							

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Document No.	Document name	Rev.	DATE
01-E	Management standards for "Environment-related substances to be controlled"	1 I X	PAGE: 2 OF 2 DATE: APR,20,2009

List of "Environment-related Substances to be Controlled ('The Controlled Substances')"

Substances
Beryllium oxide
Specific phthalates (DEHP、DBP、BBP、DINP、DIDP、DNOP、DNHP)
Hydrofluorocarbon (HFC) \cdot Perfluorocarbon (PFC)
Phosphorus certificate
Perfluorooctane sulfonates (PFOS)
Specific benzotriazole
Cobalt dichloride
Ozone depleting substance (ODS)

# 4. Allowable concentrations:

Less than 90ppm is determined as an allowable total-concentration of four heavy metals (mercury, cadmium, hexavalent chromium, and lead). Less than 5ppm is determined as an allowable cadmium-concentration in a plastic (including rubber) part.

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Component - Plastics E130155

#### NAN YA PLASTICS CORP PLASTICS 4TH DIV

3RD FL, 201 TUNG HWA NORTH RD, TAIPEI TW

### 1403G6

Polybutylene Terephthalate (PBT), furnished as pellets

	Min Thk	Flame			RTI	RTI	RTI
Color	(mm)	Class	HWI	HAI	Elec	Imp	Str
ALL	0.75	V-0	3	0	130	130	140
	1.5	V-0	2	0	130	130	140
	3.0	V-0	2	0	130	130	140

Comparative Tracking Index (CTI): 2

Dimensional Stability (%): 0

. High-Voltage Arc Tracking Rate (HVTR): 1

High Volt, Low Current Arc Resis (D495): 6

Dielectric Strength (kV/mm): 33

Volume Resistivity (10<sup>x</sup> ohm-cm): 14

ANSI/UL 94 small-scale test data does not pertain to building materials, furnishings and related contents. ANSI/UL 94 small-scale test data is intended solely for determining the flammability of plastic materials used in the components and parts of end-product devices and appliances, where the acceptability of the combination is determined by UL.

Report Date: 1991-01-11 Last Revised: 2003-10-24

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# **IEC and ISO Test Methods**

		Thickness				
Test Name	<b>Test Method</b>	Units	Tested (mm)	Value		
Flammability	IEC 60695-11-10	Class (color)	0.75	V-0 (ALL)		
			1.5	V-0 (ALL)		
			3.0	V-0 (ALL)		
Glow-Wire Flammability (GWFI)	IEC 60695-2-12	C	-	-		
Glow-Wire Ignition (GWIT)	IEC 60695-2-13	C	-	-		
IEC Comparative Tracking Index	IEC 60112	Volts (Max)	-	-		
IEC Ball Pressure	IEC 60695-10-2	C	-	-		
ISO Heat Deflection (1.80 MPa)	ISO 75-2	C	-	-		
ISO Tensile Strength	ISO 527-2	MPa	-	-		
ISO Flexural Strength	ISO 178	MPa	-	-		
ISO Tensile Impact	ISO 8256	kJ/m <sup>2</sup>	-	-		
ISO Izod Impact	ISO 180	kJ/m <sup>2</sup>	-	-		
ISO Charpy Impact	ISO 179-2	kJ/m <sup>2</sup>	-	-		

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UL iQ™ for Plastics 第 1 頁,共 1 頁

Component - Plastics E41938

#### **E I DUPONT DE NEMOURS & CO INC**

ENGINEERING POLYMERS, CHESTNUT RUN PLAZA, PO BOX 80713, WILMINGTON DE 19880

101(+)(f1), 101F(+)(f1), 101L(+)(f1), E101(+)(f1), E101L(f1), 132F(+)(f1), 135F(+)(f1)

Polyamide 66 (PA66), "Zytel", furnished as pellets

	Min Thk	Flame			RTI	RTI	RTI
Color	(mm)	Class	HWI	HAI	Elec	lmp	Str
ALL	0.71	V-2	4	0	130	75	85
	1.5	V-2	3	0	130	75	85
	3.0	V-2	2	0	130	75	85
	6.0	V-2	2	0	130	75	85

Comparative Tracking Index (CTI): 0

Dimensional Stability (%): -

High-Voltage Arc Tracking Rate (HVTR): 0

High Volt, Low Current Arc Resis (D495): 6

Dielectric Strength (kV/mm): 13

Volume Resistivity (10x ohm-cm): 14

- (+) Virgin and regrind up to 50% by weight inclusive, have the same basic material characteristics.
- (f1) Suitable for outdoor use with respect to exposure to Ultraviolet Light, Water Exposure and Immersion in accordance with UL 746C.

NOTE - (1) Material designations that are color pigmented may be followed by suffix letters and numbers. (2) Material designations may be prefixed by "ZYT" for Zytel or "MIN" for Minlon or "ZEN" for Zenite or "DEL" for Delrin or "CRA" for Crastin or "RYN" for Rynite or "THX" for Thermx or "ETPV" for ETPV grades.

ANSI/UL 94 small-scale test data does not pertain to building materials, furnishings and related contents. ANSI/UL 94 small-scale test data is intended solely for determining the flammability of plastic materials used in the components and parts of end-product devices and appliances, where the acceptability of the combination is determined by UL.

Report Date: 1996-07-29 Last Revised: 2004-09-15

**Underwriters Laboratories Inc®** 



# **IEC and ISO Test Methods**

			Thickness	
Test Name	Test Method	Units	Tested (mm)	Value
Flammability	IEC 60695-11-10	Class (color)	0.71	V-2 (ALL)
			1.5	V-2 (ALL)
			3.0	V-2 (ALL)
			6.0	V-2 (ALL)
Glow-Wire Flammability (GWFI)	IEC 60695-2-12	C	0.71	960
			1.5	960
			3.0	960
			6.0	960
Glow-Wire Ignition (GWIT)	IEC 60695-2-13	C	0.71	725
			1.5	750
			3.0	800
			6.0	800
IEC Comparative Tracking Index	IEC 60112	Volts (Max)	-	-
IEC Ball Pressure	IEC 60695-10-2	C	-	-
ISO Heat Deflection (1.80 MPa)	ISO 75-2	С	-	-
ISO Tensile Strength	ISO 527-2	MPa	-	-
ISO Flexural Strength	ISO 178	MPa	-	-
ISO Tensile Impact	ISO 8256	kJ/m <sup>2</sup>	-	-
ISO Izod Impact	ISO 180	kJ/m <sup>2</sup>	-	-
ISO Charpy Impact	ISO 179-2	kJ/m <sup>2</sup>	-	-

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Component - Plastics E41938

#### **E I DUPONT DE NEMOURS & CO INC**

ENGINEERING POLYMERS, CHESTNUT RUN PLAZA, PO BOX 80713, WILMINGTON DE 19880

#### 70G13L

Polyamide 66 (PA66), glass reinforced, "Zytel", furnished as pellets

	Min Thk	Flame			RTI	RTI	RTI
Color	(mm)	Class	HWI	HAI	Elec	Imp	Str
ALL	0.71	НВ	4	0	125	120	125
	1.5	НВ	4	0	125	120	125
	3.0	НВ	4	0	125	120	125

Comparative Tracking Index (CTI): 0

Dimensional Stability (%): 0.3

High-Voltage Arc Tracking Rate (HVTR): 1

High Volt, Low Current Arc Resis (D495): 5

Dielectric Strength (kV/mm): 22

Volume Resistivity (10<sup>x</sup> ohm-cm): 16

NOTE - (1) Material designations that are color pigmented may be followed by suffix letters and numbers. (2) Material designations may be prefixed by "ZYT" for Zytel or "MIN" for Minlon or "ZEN" for Zenite or "DEL" for Delrin or "CRA" for Crastin or "RYN" for Rynite or "THX" for Thermx or "ETPV" for ETPV grades.

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Report Date: 1996-08-06 Last Revised: 2003-10-24

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# **IEC and ISO Test Methods**

			Thickness	
Test Name	Test Method	Units	Tested (mm)	Value
Flammability	IEC 60695-11-10	Class (color)	0.71	HB75 (ALL)
			1.5	HB75 (ALL)
			3.0	HB40 (ALL)
Glow-Wire Flammability (GWFI)	IEC 60695-2-12	C	0.71	650
			1.5	650
			3.0	800
Glow-Wire Ignition (GWIT)	IEC 60695-2-13	С	0.71	675
			1.5	675
			3.0	675
IEC Comparative Tracking Index	IEC 60112	Volts (Max)	-	-
IEC Ball Pressure	IEC 60695-10-2	С	-	-
ISO Heat Deflection (1.80 MPa)	ISO 75-2	С	-	-
ISO Tensile Strength	ISO 527-2	MPa	-	-
ISO Flexural Strength	ISO 178	MPa	-	-
ISO Tensile Impact	ISO 8256	kJ/m <sup>2</sup>	-	-
ISO Izod Impact	ISO 180	kJ/m <sup>2</sup>	-	-
ISO Charpy Impact	ISO 179-2	kJ/m <sup>2</sup>	-	-

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